

# ***Chips 'N' Caps***

**TOLL FREE 1-866-590-CHIP (2447)**

## **Tape & Reel**

- Surface Mount Devices
- Axial Leads
- Radial Leads
- Tube Packaging
- Ammo Packaging
- GPAX Packaging
- Jumper Wire Tape & Reel
- De-Taping, Re-Reeling

## **Custom Assembly Services**

- Electro-Mechanical Assemblies
- Switches
- Pre-Board Assembly
- Splicing
- Gluing
- Spacer Assembly
- Color Coding

## **Component Lead Cutting and Formatting**

- Axial, Radial & Surface Mount Leads
- Through-Hole to Surface Mount Conversions
- T0-92 Transistors
- Crimps, Snap-in, Stand-off

## **Screening**

- Commercial (0° to +70°) up to Industrial (-40° to +85°), automotive (-40° to +125°), and Military (-55 ° to +125°).

## **MIL-STD-883 And Other Testing Capabilities**

- Acceleration
- Atmosphere/Altitude to 80,000 ft.
- Barometric Pressure Testing
- Bond Pull
- Bond Strength
- Burn-in Testing to +200°C
- Capacitance Testing
- Centrifuge
- Class S Testing for Space
- Clean Room Microelectronic Packaging
- Commercial Testing
- Constant Acceleration/Centrifuge
- Cross Sectioning
- Custom Hardware/Software

### **MIL-STD-883 And Other Testing Capabilities (Con't.)**

- Custom IC & Transistor Packaging
- Destructive Testing
- Destructive Physical Analysis - DPA on Components
- Die Qualification
- Die Shear Strength Test
- Die Penetrant
- Dust Testing
- EDAX
- Electrical Characteristics
- Electrical Testing
- Element Evaluation
- Environmental Stress Screening
- Environmental Testing
- Equivalent Screening for JAN thru JANS
- External Visual
- Failure Analysis
- Fine & Gross Leak Testing
- Fungus Test
- HAST Testing
- Helium Leak Testing on Components
- Humidity Test
- Immersion
- Industrial Temperature Testing
- Internal Visual, Hybrid
- Internal Visual inspection for DPA
- Internal Visual Mechanical
- Internal Visual Monolithic
- Lead Forming
- Lead Integrity
- Lead Pull for PG
- Lid Torque
- Marking
- Mechanical Shock
- Moisture Resistance
- Non-Destructive Testing
- PIND Particle Impact Noise Detection
- Qualification and Quantity Conformance Inspection
- Recertification
- Reliability Testing
- Physical Dimensions
- Power Burn-In
- Radiography
- Resistance to Solvents
- SEM Analysis - Scanning Electron Microscope
- Salt Spray
- Salt Atmosphere
- Seal - Leak Test
- Shock Testing
- Solderability

### **MIL-STD-883 And Other Testing Capabilities (Con't.)**

- Serialize Components
- Solderability Testing
- Space Level Testing
- Stabilization Bake
- Steady State Life
- Temperature Cycling (-200°C to +200°C)
- Thermal Shock Testing (+200°C)
- Upscreening
- Vibration Testing - Up to 500 lb.
- Vibration Viable Frequency
- Wafer Probing
- X-Ray